

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC037N08NS5T	**Issued**	15. May 2021
MA#	MA004508890		
Package	PG-TDSON-8-7	**Weight***	118.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.175	0.99	0.99	9882	9882
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		318	
	non noble metal	copper	7440-50-8	37.762	31.76	31.80	317529	317942
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	376	376
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		722	
	plastics	epoxy resin	-	6.787	5.71		57074	
	inorganic material	silicondioxide	60676-86-0	36.085	30.34	36.12	303434	361230
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12207	12207
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1392	1392
solder	non noble metal	tin	7440-31-5	0.033	0.03		279	
	noble metal	silver	7440-22-4	0.042	0.03		349	
	non noble metal	lead	7439-92-1	1.587	1.33	1.39	13342	13970
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.52	9.53	95188	95312
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.74	18.77	187445	187689
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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